



SOT1161-2

XQFN16, plastic, extremely thin quad flat package; no leads;
16 terminals; 2.6 mm x 1.8 mm x 0.50 mm body

5 June 2017

Package information

1. Package summary

| | |
|---------------------------------------|---|
| Terminal position code | Q (quad) |
| Package type descriptive code | XQFN16 |
| Package type industry code | XQFN16 |
| Package style descriptive code | XQFN (extremely thin quad flatpack; no leads) |
| Package body material type | P (plastic) |
| Mounting method type | S (surface mount) |
| Issue date | 24-1-2017 |
| Manufacturer package code | SOT1161 |

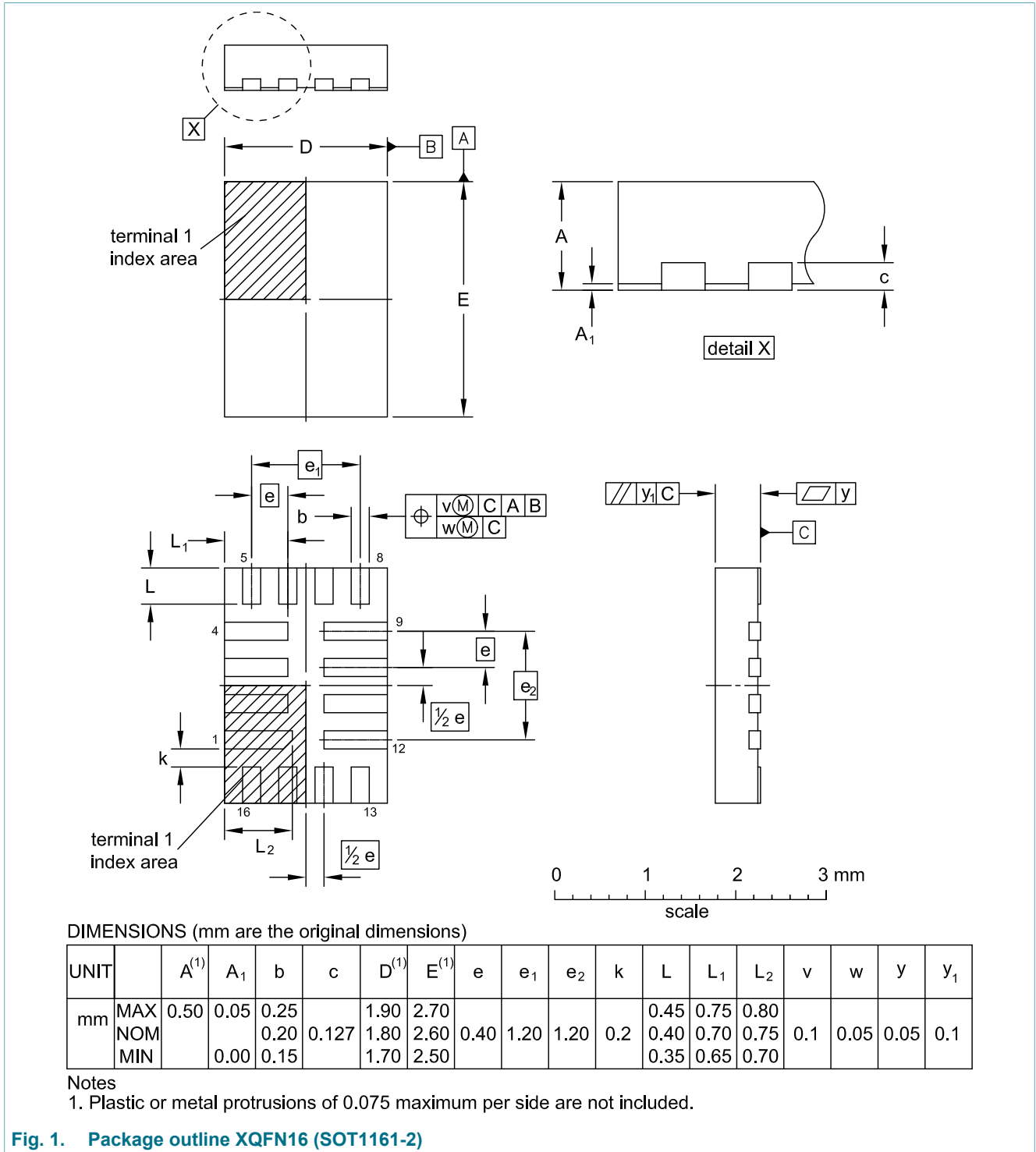
Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-----|-----|-----|-----|------|
| D | package length | 1.7 | - | 1.8 | 1.9 | mm |
| E | package width | 2.5 | - | 2.6 | 2.7 | mm |
| e | nominal pitch | - | - | 0.4 | - | mm |
| n ₂ | actual quantity of termination | - | - | 16 | - | |



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2. Package outline



XQFN16, plastic, extremely thin quad flat package; no leads; 16 terminals; 2.6 mm x 1.8 mm x 0.50 mm body

3. Soldering

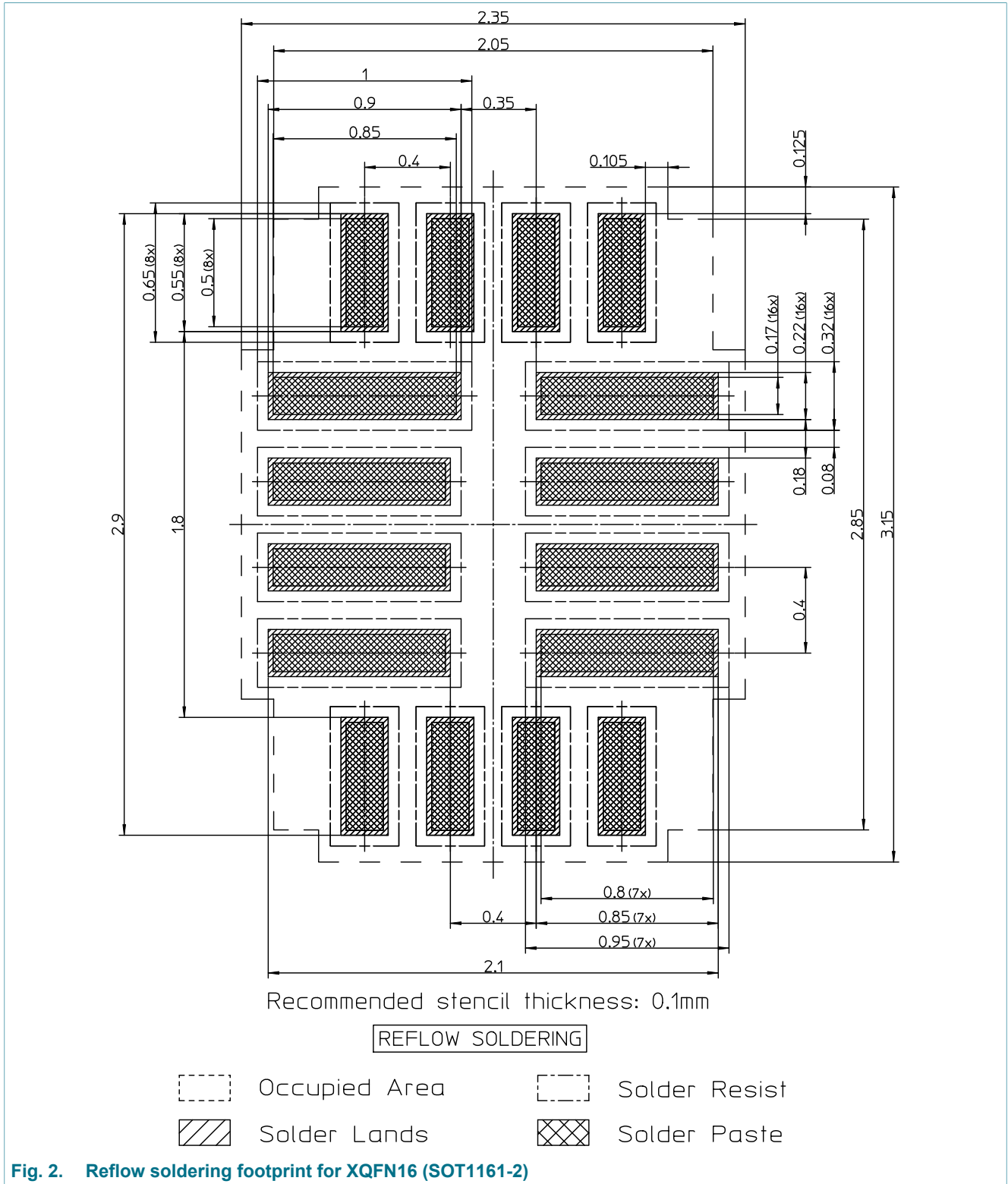


Fig. 2. Reflow soldering footprint for XQFN16 (SOT1161-2)

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4. Legal information

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